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(54) Title: PATTERNED SUBSTRATE PRE-WETTING COMPOSITION, USE OF PRE-WETTING COMPOSITION FOR APPLI-
CATION DIRECTLY ONTO PATTERNED SUBSTRATE, METHOD FOR MANUFACTURING RESIST PATTERN, METHOD
FOR MANUFACTURING PROCESSED SUBSTRATE, AND METHOD FOR MANUFACTURING DEVICE

(57) Abstract: A patterned substrate pre-wetting composition includes 0.05 to 40 mmHg of vapor pressure at 20°C, and 15 to 60 dyn /
cm of surface tension at 20°C. Viscosity of the patterned substrate pre-wetting composition at 20°C is 0.5 to 20.0 cP. The patterned
substrate pre-wetting composition contains an organic solvent (A), and optionally, the organic solvent (A) is one organic solvent or a
mixture of two or more organic solvents.



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